



CENTER FOR NANOSCALE MATERIALS TOOLS AND CAPABILITIES

Nanofabrication and Devices

Lithography

- Electron Beam Lithography JEOL 8100FS*
- Electron Beam Lithography: Raith 150*
- FIB/SEM: FEI Nova 600 NanoLab*
- Heidelberg MLA150 Maskless Lithography*
- Interferometric Lithography System
- Laser Pattern Generator (Microtech LW405, Direct Write Optical Lithography)
- SUSS MA6/BA6: Contact aligner for front side and front-to-back side alignment
- Wafer Priming Oven: YES-TA Series
- Stepper: ASML PAS 5000 Wafer Stepper

Post-Processing

- AS-One 150 Rapid Thermal Processor
- Cleaving Machine: LatticeGear Ax 420
- Critical Point Dryer (Leica CPD030)
- ADT Dicing Saw*

Wet Chemistry

- Electroplating (Au, Cu, Fe, Ni, Pt)
- Selective Wet Chemical Etching

Dry Etching

- Hydrofluoric Acid Vapor Etcher
- PlasmaTherm Deep Reactive Ion Etcher for Silicon (DRIE)
- RIE Oxford ICP Etcher (6-inch)
- RIE March CS-1701, Chlorine Chamber
- RIE March CS-1701, Fluorine Chamber
- RIE Oxford PlasmaLab 100, Chlorine and Fluorine Chambers
- Xactix X4 Xenon Difluoride Etcher

Inspection and Metrology

- Bruker FastScan AFM*
- Filmetrics f40 Thin Film Analyzer*
- Four Point Probe
- Keyence 3D Laser Scanning Confocal Microscope, VK-X1000*
- Laser Confocal Microscope OLS4100
- Optical Microscope: Olympus MX-61
- Potentiostat
- Three-Dimensional Contact Profilometer: Dektak 8
- UVISEL Spectroscopic Ellipsometer: Horiba Jobin Yvon
- Scanning Electron Microscope VEGA 3

Deposition

- AJA Oxide Sputtering, 3-inch targets*
- Temescal FC2000 Electron Beam Evaporator
- AJA Sputtering, 2-inch targets*
- Lambda Microwave Plasma CVD System: Nanocrystalline Diamond Deposition*

- Oxford Plasmalab 100 Inductively Coupled Plasma Enhanced Chemical Vapor Deposition

- Thermal/PECVD System for CNT and Graphene Synthesis
- AJA Dielectric Sputtering System*
- AJA Metal Sputtering System*
- Atomic Layer Deposition (Arradiance Gemstar)*
- Integrated UV-Ozone Cleaner and Molecular Vapor Coater (Nanonex Ultra-100)

Piezo-Optomechanical Spectrometer (POMS)

Ultralow Temperature/Strong Magnetic Field Measurements*

- BlueFors LD400 Dilution Refrigerator System: <10mK base temp, free-space optical access, dc wires, microwave cables, high-pressure fill lines, expedited top-loading sample mechanism, low-noise amplifiers for qubit research
- AMI Superconducting Vector magnet: 5T in Z axis, 1T in Y axis, 10mG field stability, integrated persistent switches

Wear/Friction Measurements

- Multifunctional Tribometer with controlled environments*
- PicoIndenter, *in situ* TEM (PI-95)
- Sonotek Ultrasonic Spray Coating System

Theory and Modeling

CNM High-Performance Computing Cluster (Carbon)

Computational Nanoscience Software and Modeling Expertise

- BLAST (Bridging Length/Timescales via Atomistic Simulation Toolkit)
- Dacapo
- Density-Functional-Based Tight-Binding (DFTB)
- FANTASTX (Fully Automated Nanoscale to Atomistic Structure from Theory and eXperiment)
- GPAw, a real space, grid-based DFT-PAW code
- MPI-Based Parallel Versions of Nanophotonics
- Time-Domain Nanophotonics Simulation Package
- VASP, Ab-Initio Molecular Dynamics Calculations
- Other specialized analysis software or modeling expertise

Nanophotonics and Biofunctional Structures

Adiabatic Demagnetization Refrigerator (ADR)*

Bench-Top Spectroscopy

- UV-Visible Absorption
- Emission (uv-vis, NIR, MIR)
- FTIR Absorption
- Circular Dichroism
- Cryostat/Temperature Control

Magneto-optical Microscope (MOM)

Magneto-Electro-Optical Spectrometer (MEOS)

Raman Spectroscopy

- Temperature-Controlled Stage
- Electron Paramagnetic Resonance Spectroscopy (EPR: CW and Pulsed)

Electrochemical Workstation (BASI Epsilon)

GC-MS (Agilent 5975C Series GC/MSD)

HPLC (LabAlliance)

Isothermal Titration Calorimetry (ITC)

ZetaSizer Nano, Malvern (particle size potential)

Time-Resolved Emission Spectroscopy

- Time-Correlated Single Photon Counting (TCSPC) Spectroscopy (uv-vis, NIR)
- TCSPC Microscopy (400 – 800 nm)
- Visible and Near-IR TCSPC with Streak Camera
- Near-IR TCSPC with Superconducting Nanowire Single Photon Detector

Transient Absorption Spectroscopy

- Visible Probe
- Near-IR Probe
- Mid-IR Probe
- THz Probe
- Cryostat

Visible and Near-IR Microscopy

- Lamp Illumination
- Laser Illumination
- Visible Detection
- Near-IR Detection
- Cryostat

Correlation/Antibunching Measurements

- Visible (350 – 800 nm) Detection with APD Detectors
- NIR (800 nm – 2 μm) Detection with Superconducting Nanowire Single-Photon Detectors (SNSPD)

- Field Emission Scanning Electron Microscope, JEOL JSM-7500F**
- Laser Scanning Confocal Microscope, Zeiss LSM 510 Meta**
- Optical Microscope, Zeiss Axio Imager Z1 M Upright***
- General Wet Lab Space for Sample Prep**
- Surface Preparation**
 - Harrick Plasma Cleaner
 - UVO Surface Cleaner
- Autoclaves**
- Centrifuges**
- Drop Shape Analysis Tool**
- Lyophilizer**
- Ossila Slot-Die Coater**
- Rotary Evaporator**
- Schlenk Lines**
- Solar Simulator, Oriel**
- Internal/External Quantum Efficiency Measurement System (Oriel IQE-200)**
- Glove Box, MBraun LabMaster 130**
- Integrated Glove Box System**
- Biological Safety Cabinets, Labconco Purifier Delta Series (Class II, B2)**
- Peptide Synthesizer***
- Synthesis**
 - Surface Modification of Nanoparticles
 - Functionalization
 - Quantum Dots
 - Metal Nanoparticles
 - Metal Oxide Nanoparticles
- Post Processing**
 - External Field, Ultrasound, Dip-coating

Quantum and Energy Materials

- Synchrotron X-Ray Scanning Tunneling Microscopy (SX-STM) at APS Sector 4***
- Agilent Inductively Coupled Plasma Optical Emission Spectroscopy ICP-OES**
- Electrical Characterization**
 - Associated High-Sensitivity Test Systems
 - Keithley 4200-SCS/F Semiconductor Parameter Analyzer
- FT-IR with Hyperion Microscope, Bruker Vertex 70**
- Langmuir-Blodgett, Kibron MicroTrough X**
- Luminescence spectrometer, Perkin-Elmer LS 55**
- Magnetometry**
 - Quantum Design MPMS-XL
 - Quantum Design PPMS-9
- Physical Vapor Deposition, common loadlock is shared***
 - Lesker E-beam Evaporator (PVD250)
 - Lesker Sputtering System (CMS18)
- Rheometer, AntonPaar Physica MCR301**
- Rheo-XPCS at APS Sector 8**
- Scanning Probe Microscope, Veeco MultiMode 8**
 - PeakForce Quantitative Nanomechanical Mapping, Tapping
 - Fluid Imaging
 - Low Current STM
 - Magnetic Force

- Variable Temperature Imaging**
- Spin Coater, Laurell WS-400, not for lithography resist work**
- Synthesis Lab – Inorganic Crystals**
- Thermal Analysis**
 - Differential Scanning Calorimetry, Mettler Toledo 823
 - Thermogravimetric Analysis, Mettler Toledo 851
- Tube furnaces (1-inch)**
 - Argon, Oxygen, MTI
- UV-Vis-NIR spectrometers, Perkin-Elmer Lambda 950 and Cary 5000**
- VT-UHV-Atomic Force Microscope/Scanning Tunneling Microscope (AFM/STM; Omicron VT-AFM XA)***
 - Contact AFM
 - Magnetic Force Microscopy
 - Non-Contact AFM
 - Scanning Tunneling Spectroscopy
- Optical UHV VT STM/AFM***
 - Lasers for Optical UHV VT STM/AFM
 - Contact and non-contact AFM, MFM
 - Scanning Tunneling Spectroscopy
- UHV Cryo SFM with 6T Magnetic Field, Omicron**
- Low Temperature Scanning Tunneling Microscopy (LT-STM, Createc)***
- Laser Scanning Interferometric Microscope**
- SPM Tip Etching**
- West-Bond Wire Bonder***
- X-Ray Diffractometer Bruker D2 Phaser**
- X-Ray Diffractometer Bruker D8 Discover**
 - Grazing Incidence, High-Resolution Four-Circle, Reciprocal Space Mapping, Reflectivity, Rocking Curves, Eiger2
- Electron and X-Ray Microscopy**
- Hard X-Ray Nanoprobe, Sector 26***
 - Multimodal Chemical and Structural Nanoimaging
 - Scanning Nanodiffraction, Bragg Ptychography
- UEM: Ultrafast Electron Microscopy***
 - Temporal resolution ca. 1 ps
 - Spatial resolution ca. 1 nm
 - Energy resolution ca 1 eV
 - Pump laser wavelengths: 515, 325-450, 650-900, 1030, and 1200-2000 nm
 - Repetition rate: 10-500 kHz (fs laser), 1-100 kHz (ns laser)
- ACAT: Argonne Chromatic Aberration-Corrected TEM***
 - Cc/Cs-Corrected HRTEM and EFTEM Imaging and Diffraction
- Talos F200X (S)TEM***
 - TEM Imaging and Diffraction (80, 120, & 200kV)
 - STEM Imaging (HAADF & BF; DF2, DF4, DPC, 80, 120, & 200 kV)
 - XEDS, Super-X, 4SDD EDX System
 - EDS Mapping (profiles and/or maps)
 - Lorentz Imaging (200 kV)
 - Tomography (200 kV)
- Field Emission Transmission Electron Microscope, JEOL JEM-2100F***
 - TEM Imaging and Diffraction (200 kV)
- EFTEM Imaging (200 kV)**
- EELS (200 kV)**
- XEDS**
- Tomography (200 kV)**
- Special Specimen Holders**
 - Liquid Flow Holder (room temp)
 - Gas Flow Holder (room temp or 100 – 500C)
 - Single-Tilt Heating Specimen Holder (T <= 900C)
- FEI Tecnai F20ST (S)TEM***
 - TEM Imaging and Diffraction (80, 120, & 200 kV)
 - STEM Imaging (HAADF & BF; 80, 120, & 200 kV)
 - EFTEM Imaging and Diffraction (120 & 200 kV)
 - EELS (120 & 200 kV)
 - XEDS
 - Spectrum Imaging (profiles and/or maps)
 - Lorentz Imaging (200 kV)
 - Tomography (200 kV)
 - Special Specimen Holders:
 - Double-Tilt Liquid N2-Cooled (T >= 97 K)
 - Double-Tilt Heating
 - Tilt-Rotate Liquid He-Cooled
- Zeiss 1540XB FIB-SEM**
 - TEM Sample Preparation
 - 3D FIB-SEM Serial Sectioning
 - SEI & BSE Imaging, FIB cross-sectioning
- Zeiss NVision FIB-SEM***
- FEI Quanta 400F (E)SEM***
 - SEI & BSE Imaging (2 – 30 kV)
 - High-Vacuum Mode (P < 10-5 torr)
 - Low-Vacuum Mode (P ~ 0.1 – 2 torr)
 - ESEM Mode (P ~ 2 – 20 torr)
 - ESEM Mode with a gas other than air or water vapor
 - Peltier-Cooled Stage (T ~ 248 – 328 K)
 - Heating Stages (T < 1273 K or T < 1773 K)
- Hitachi S-4700-II SEM***
 - SEI & BSE Imaging (0.5 – 30 kV)
 - XEDS Mapping or Spectrum Imaging
- Specimen Preparation Resources (not FIB)**
 - Cutting from bulk, Grinding/Polishing, Dimpling, Ion-Milling*, Vacuum-Coating with gold or carbon
- Data Analysis**
 - Image Processing
 - HRTEM Image Simulation
 - Diffraction Pattern Simulation
 - XEDS Analysis (inc. spectrum images)
 - EELS Analysis (inc. spectrum images or EFTEM spectrum images)

*Indicates remote operation is available